

Product / Process Change Notification



N° 2013-134-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Implementation of Electro-Chemical-Deposition (ECD) center at Infineon wafer fab in Kulim and Data Sheet change for SPOC

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **06. July 2014**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response within the given time limit we consider this as the acceptance of the PCN.

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SUBJECT OF CHANGE: Implementation of Electro-Chemical-Deposition (ECD) center at Infineon wafer fab in Kulim (Infineon Technologies Kulim Sdn Bhd) and data sheet change.

PRODUCTS AFFECTED:	Type	SP n°	OPN	Package
	BTS54040-LBA	SP000887550	BTS54040LBA AUMA1	PG-TSON-24-3
	BTS54040-LBE	SP000887552	BTS54040LBE AUMA1	PG-TSON-24-3
	BTS54220-LBA	SP000887554	BTS54220LBA AUMA1	PG-TSON-24-3
	BTS54220-LBE	SP000887556	BTS54220LBE AUMA1	PG-TSON-24-3
	BTS55032-LBA	SP000919412	BTS55032LBA AUMA1	PG-TSON-24-3
	BTS56033-LBA	SP000915094	BTS56033LBA AUMA1	PG-TSON-24-3

- REASON OF CHANGE:**
- Infineon extends the wafer plant manufacturing capacity in order to meet the increasing market demand of electronic components and such way to secure the supply channel
 - Optimize logistic flow by enabling ECD implemented in Infineon wafer plant in Kulim (Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia).
 - Data sheet parameter optimization

DESCRIPTION OF CHANGE:	OLD	NEW
■ Wafer Plant (included ECD process)	Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies AG, Regensburg, Germany	Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia or Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies AG, Regensburg, Germany
■ Wafer Test	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia or Infineon Technologies Austria AG, Villach, Austria
■ Data sheet change		See 3_cip13134

PRODUCT IDENTIFICATION: Product identification by MA- and Baunumbers possible
No change in SP ordering number

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TIME SCHEDULE:

■ Final qualification report:	available
■ First samples available:	available
■ Start of delivery:	01-December-2014 or earlier after customer release
■ Last order date of unchanged product:	not applicable
■ Last delivery date of unchanged product:	not applicable

ASSESSMENT:

No impact on parameters and reliability proven via technology and product qualification. Product performance according to specification

The tester platform verification is performed via the **Advanced Measurement System Analysis (AMSA)** methodology, which includes a test result correlation and a bin sorting verification.

No impact on quality and reliability. Processes are optimized to meet the identical product performance according to specification.

DOCUMENTATION:

3_cip13134	Description of data sheet changes
4_cip13134	Data sheets